

The diagram illustrates a chemical processing system for a silicon wafer. A central **Process Chamber/Motor** (14) contains a **Silicon Wafer** (12). The chamber is connected to several supply lines: **Ozone Generator** (34) via line 56; **HF Supply** (32) via line 42; **HCl Supply** (30) via line 40; and **NH4OH or Other Chemical Supply** (28) via line 44. A **Hot DI Water Supply** (22) is connected via line 24. A dashed line 38 indicates a connection to a component 34. A dashed line 32 connects the HF Supply to the chamber. A dashed line 40 connects the HCl Supply to the chamber. A dashed line 44 connects the NH4OH supply to the chamber. A dashed line 30 connects the HCl Supply to the chamber. A dashed line 28 connects the NH4OH supply to the chamber. A dashed line 24 connects the Hot DI Water Supply to the chamber. A dashed line 22 connects the Hot DI Water Supply to the chamber. A dashed line 20 connects the Hot DI Water Supply to the chamber. A dashed line 18 connects the Hot DI Water Supply to the chamber. A dashed line 16 connects the Hot DI Water Supply to the chamber. A dashed line 14 connects the Hot DI Water Supply to the chamber. A dashed line 12 connects the Hot DI Water Supply to the chamber. A dashed line 10 connects the Hot DI Water Supply to the chamber. A dashed line 8 connects the Hot DI Water Supply to the chamber. A dashed line 6 connects the Hot DI Water Supply to the chamber. A dashed line 4 connects the Hot DI Water Supply to the chamber. A dashed line 2 connects the Hot DI Water Supply to the chamber. A dashed line 1 connects the Hot DI Water Supply to the chamber. A dashed line 0 connects the Hot DI Water Supply to the chamber.

Fig. 1

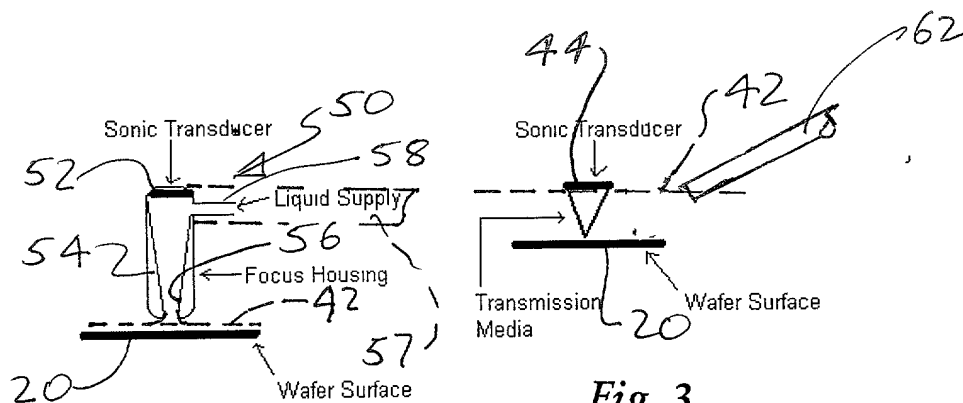
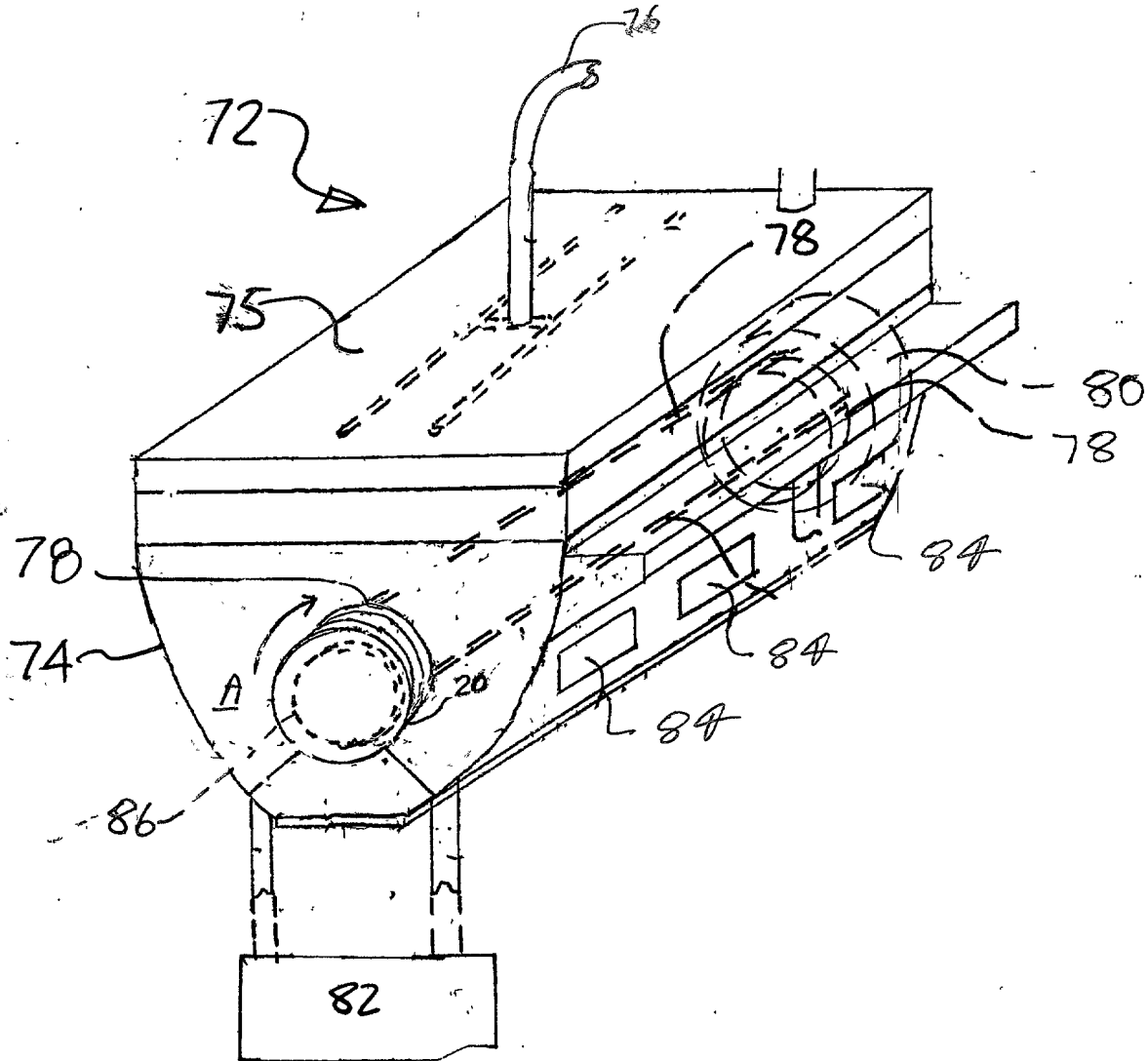


Fig. 2

Fig. 4

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